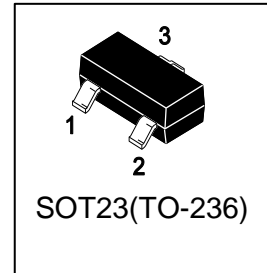


LN2308ELT1G

S-LN2308ELT1G

60V N-Channel Power MOSFET

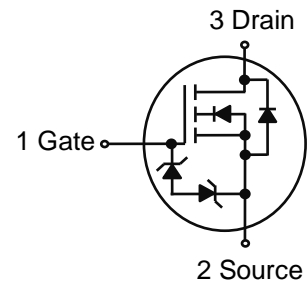


1. FEATURES

- Gate to Source ESD Protected
- Super high density cell design for extremely low RDS(ON).
- Exceptional on-resistance and maximum DC current capability.
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

2. APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC



3. DEVICE MARKING AND ORDERING INFORMATION

| Device | Marking | Shipping |
|-------------|---------|-----------------|
| LN2308ELT1G | E08 | 3000/Tape&Reel |
| LN2308ELT3G | E08 | 10000/Tape&Reel |

4. MAXIMUM RATINGS(Ta = 25°C)

| Parameter | Symbol | Limits | Unit |
|-------------------------------------|----------|----------|------|
| Drain-Source Voltage | VDSS | 60 | V |
| Gate-to-Source Voltage – Continuous | VGS | ±20 | V |
| Drain Current | ID | 2.6 | A |
| – Continuous TA = 25°C | | | |
| – Continuous TA = 70°C | | | |
| – Pulsed(Note 1) | IDM | 10.4 | |
| Junction and Storage temperature | TJ, Tstg | -55~+150 | °C |

5. THERMAL CHARACTERISTICS

| Parameter | Symbol | Limits | Unit |
|--|--------|--------|------|
| Maximum Power Dissipation | PD | 0.9 | W |
| Thermal Resistance, Junction-to-Ambient(Note 2) | RθJA | 140 | °C/W |
| Junction-to-Case | RθJC | 105 | |

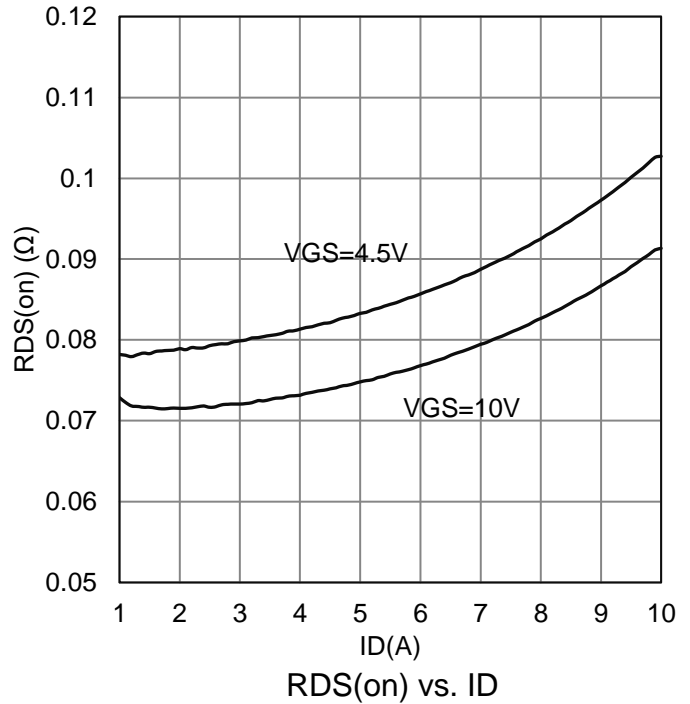
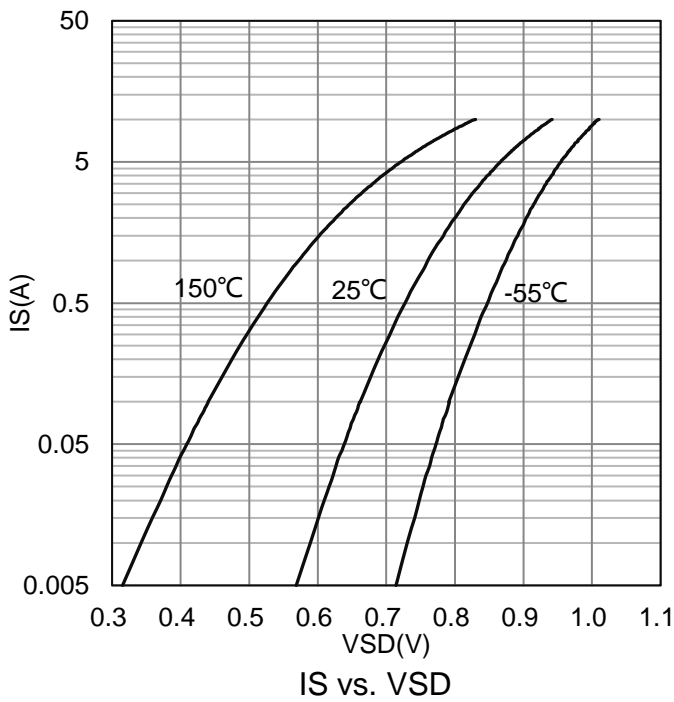
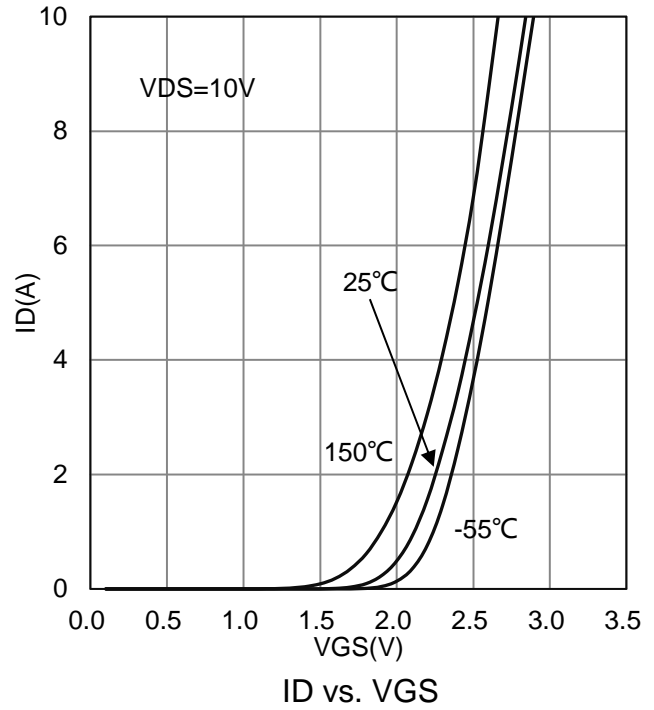
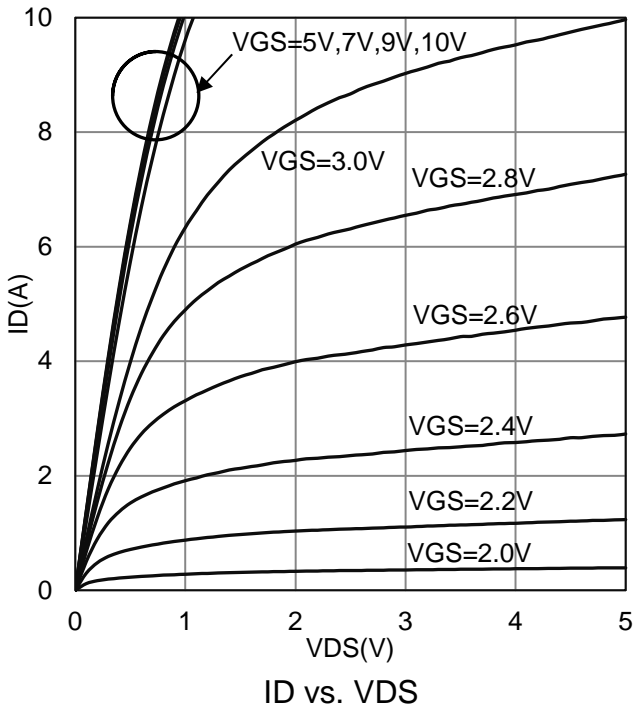
1. Repetitive Rating: Pulse width limited by the Maximum junction temperature.
2. 1-in² 2oz Cu PCB board.

6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

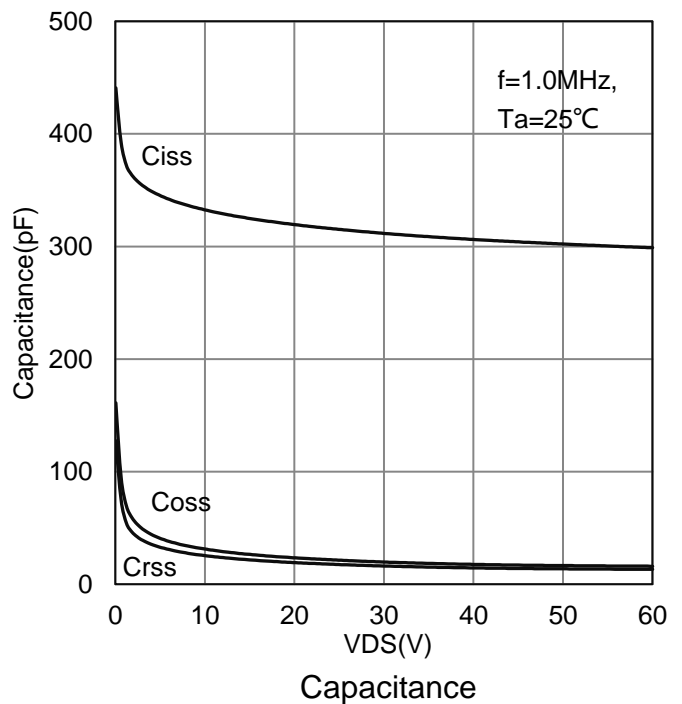
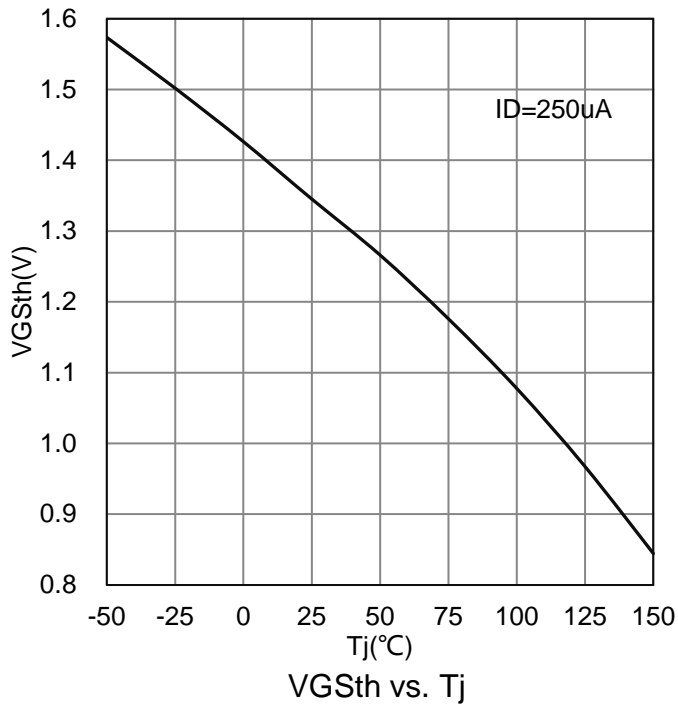
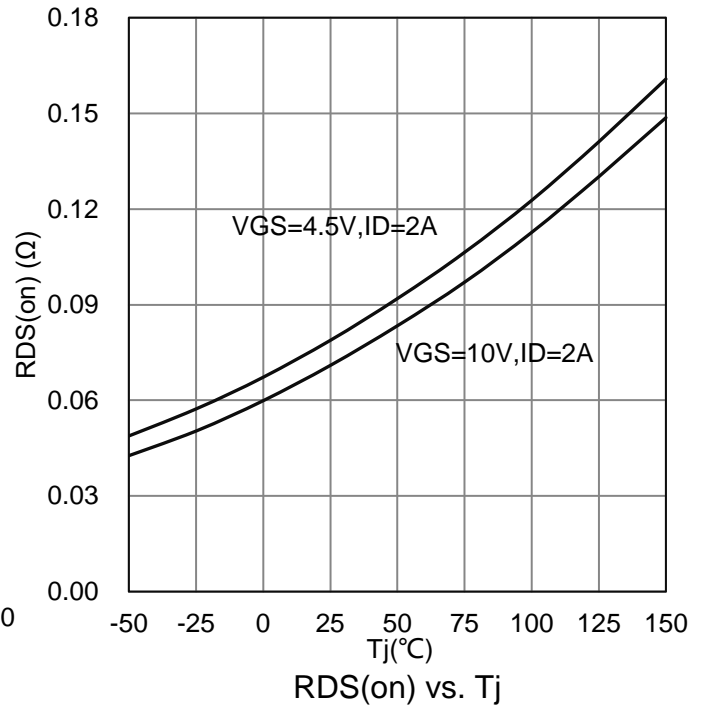
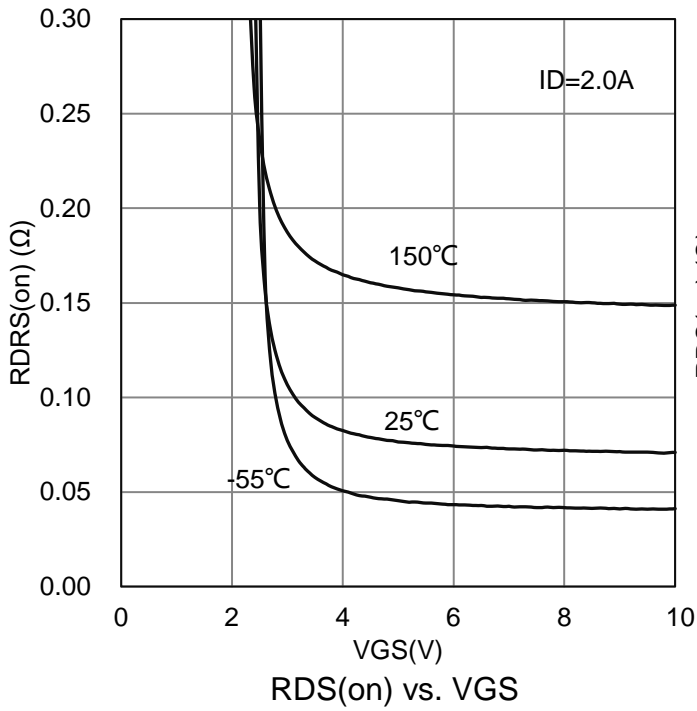
| Characteristic | Symbol | Min. | Typ. | Max. | Unit |
|--|---|---------|--------|------------|------|
| Static | | | | | |
| Drain–Source Breakdown Voltage (VGS = 0, ID = 250μA) | V(BR)DSS | 60 | - | - | V |
| Gate Threshold Voltage (VDS = VGS, ID = 250μA) | VGS(th) | 1 | 1.5 | 2.5 | V |
| Gate Body Leakage (VDS =0V, VGS =±20V) | IGSS | - | - | ±10 | μA |
| Zero Gate Voltage Drain Current (VDS =48V, VGS =0V) | IDSS | - | - | 1 | μA |
| Static Drain–Source On–State Resistance (VGS = 10 V, ID = 2 A) (VGS = 4.5 V, ID = 2 A) | RDS(on) | - - | - - | 100 120 | mΩ |
| Diode Forward Voltage (IS =0.5A, VGS =0V) | VSD | - | 0.7 | 1.3 | V |
| Dynamic | | | | | |
| Total Gate Charge | (VDS =30V, VGS =4.5V, ID =2A) | Qg | - | 3.3 | nC |
| Gate–Source Charge | | Qgs | - | 0.7 | |
| Gate–Drain Charge | | Qgd | - | 1.4 | |
| Input capacitance | (VDS =30V, VGS =0V, f=1MHz) | Ciss | - | 312 | pF |
| Output Capacitance | | Coss | - | 20 | |
| Reverse Transfer Capacitance | | Crss | - | 16 | |
| Turn-On Delay Time | (VDD =30V, RL =30Ω, ID =1A, VGEN =10V, RG =3Ω) | td(on) | - | 3.6 | ns |
| Turn-On Rise Time | | tr | - | 10.2 | |
| Turn-Off Delay Time | | td(off) | - | 17.1 | |
| Turn-Off Fall Time | | tf | - | 11 | |
| Gate Resistance (VDS=0V ,VGS=0V, f=1.0MHz) | Rg | - | 4.8 | - | Ω |

3. Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%.

7. ELECTRICAL CHARACTERISTICS CURVES



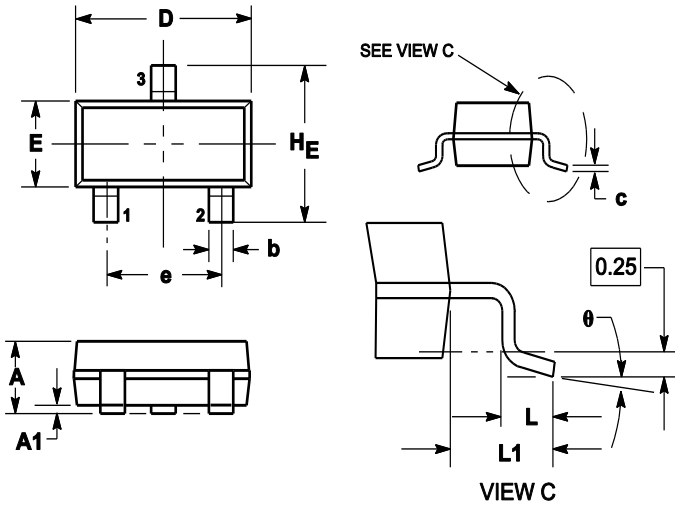
7. ELECTRICAL CHARACTERISTICS CURVES(Con.)



8.OUTLINE AND DIMENSIONS

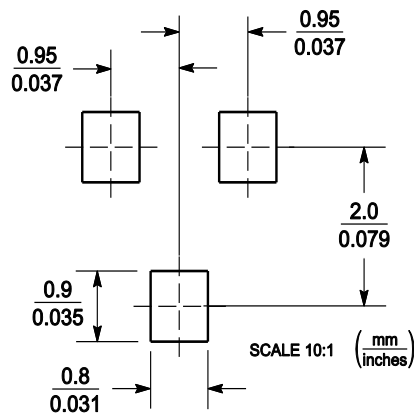
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



| DIM | MILLIMETERS | | | INCHES | | |
|-------|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.89 | 1 | 1.11 | 0.035 | 0.04 | 0.044 |
| A1 | 0.01 | 0.06 | 0.1 | 0.001 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.5 | 0.015 | 0.018 | 0.02 |
| c | 0.09 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 2.80 | 2.9 | 3.04 | 0.11 | 0.114 | 0.12 |
| E | 1.20 | 1.3 | 1.4 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.9 | 2.04 | 0.07 | 0.075 | 0.081 |
| L | 0.10 | 0.2 | 0.3 | 0.004 | 0.008 | 0.012 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.029 |
| HE | 2.10 | 2.4 | 2.64 | 0.083 | 0.094 | 0.104 |
| theta | 0° | --- | 10° | 0° | --- | 10° |

9.SOLDERING FOOTPRINT



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